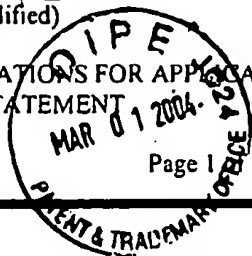


LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S
INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)



Page 1 of 1

Attorney Docket No.:
FIS920030187US1Serial No.:
10/605,310Applicant:
Dureseti Chidambarao, et al.Filing Date:
September 22, 2003Group:
2818

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINERS INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

P 0		Kern Rim, et al., "Transconductance Enhancement in Deep Submicron Strained-Si n-MOSFETs", International Electron Devices Meeting, 26, 8, 1, IEEE, September 1998.
		Kern Rim, et al., "Characteristics and Device Design of Sub-100 nm Strained Si N- and PMOSFETs", 2002 Symposium On VLSI Technology Digest of Technical Papers, IEEE, pp 98-99.
		Gregory Scott, et al., "NMOS Drive Current Reduction Caused by Transistor Layout and Trench Isolation Induced Stress", International Electron Devices Meeting, 34.4.1, IEEE, September 1999.
		F. Ootsuka, et al., "A Highly Dense, High-Performance 130nm node CMOS Technology for Large Scale System-on-a-Chip Application", International Electron Devices Meeting, 23.5.1, IEEE, April 2000.
		Shinya Ito, et al., "Mechanical Stress Effect of Etch-Stop Nitride and its Impact on Deep Submicron Transistor Design", International Electron Devices Meeting, 10.7.1, IEEE, April 2000.
		A. Shimizu, et al., "Local Mechanical-Stress Control (LMC): A New Technique for CMOS-Performance Enhancement", International Electron Devices Meeting, IEEE, March 2001.
P D		K. Ota, et al., "Novel Locally Strained Channel Technique for high Performance 55nm CMOS", International Electron Devices Meeting, 2.2.1, IEEE, February 2002.

EXAMINER

PHUC T. DANG

DATE CONSIDERED

11/12/2004

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449 (Modified)			ATTY. DOCKET NO. FIS920030187US1		SERIAL NO. 10/605,310	
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT			APPLICANT: Chidambarao, Dureseti, et al.			
(Use several sheets if necessary) DEC 05 2003			FILING DATE: 9/22/03		GROUP: Unassigned 2818	

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS							
EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPRO.)	
P D ↑	US 6,228,694 B1	5/8/2001	Doyle et al.	T	T		
	US 6,406,973 B1	6/18/2002	Lee				
	US 6,281,532 B1	8/28/2001	Doyle et al.				
	5,683,934	11/4/97	Candelaria				
	US 6,368,931 B1	4/9/2002	Kuhn, et al.				
	5,310,446	5/10/94	Konishi et al.				
	4,853,076	8/1/89	Tsaur et al.				
	US 2002/0090791 A1	7/11/2002	Doyle et al.				
	US 2002/0074598 A1	6/20/2002	Doyle et al.				
	US 6,509,618 B2	1/21/2003	Jan et al.				
	US 6,476,462 B2	11/5/2002	Shimizu et al.				
	US 6,362,082 B1	3/26/2002	Doyle et al.				
	US 6,228,694 B1	5/8/2001	Doyle et al.				
	5,565,697	10/15/96	Asakawa et al.				
	US 2003/0040158 A1	2/27/2003	Saitoh				
	US 2002/0086472 A1	7/4/2002	Roberds et al.				
	US 6,521,964 B1	2/18/2003	Jan et al.				
	US 6,506,652 B2	1/14/2003	Jan et al.				
	US 5,081,513	1/14/1992	Jackson, et al.				
	US 3,602,841	8/31/1971	McGroddy				
US 6,531,740	3/11/2003	Bosco, et al.					
US 6,531,369	3/11/2003	Ozkan, et al.					
US 6,501,121	12/31/2002	Yu, et al.					
US 6,498,358	12/24/2002	Lach, et al.					
US 6,493,497	12/10/2002	Ramdani, et al.					
US 6,403,975	6/11/2002	Brunner, et al.					
US 6,361,885	3/26/2002	Chou					
US 6,255,169	7/3/2001	Li, et al.					
V	US 6,246,095 B1	6/12/2001	Brady, et al.				
P D	US 6,165,383	12/26/2000	Chou	T	T		

PD	US 6,133,071	10/17/2000	Nagai				
	US 6,046,464	4/4/2000	Schetzina				
	US 6,025,280	2/15/2000	Brady, et al.				
	US 5,940,736	8/17/1999	Brady, et al.				
	US 5,880,040	3/9/1999	Sun, et al.				
	US 5,861,651	1/19/1999	Brasen, et al.				
	US 5,679,965	10/21/1997	Schetzina				
	US 5,670,798	9/23/1997	Schetzina				
	US 5,561,302	10/1/1996	Candelaria				
	US 5,471,948	12/5/1995	Burroughes, et al.				
	US 5,459,346	10/17/1995	Asakawa, et al.				
	US 5,391,510	2/21/1995	Hsu, et al.				
	US 5,371,399	12/6/1994	Burroughes, et al.				
	5,108,843	4/28/92	Ohtaka et al.				
	5,060,030	10/22/91	Hoke				
	4,958,213	9/18/90	Eklund et al.				
	4,665,415	5/12/87	Esaki et al.				
	5,989,978	11/23/99	Peidous				
	US 6,284,626 B1	9/4/2001	Kim				
	US 6,274,444 B1	8/14/2001	Wang				
	US 6,261,964 B1	7/17/2001	Wu et al.				
	US 6,221,735 B1	4/24/2001	Manley et al.				
	6,117,722	9/12/2000	Wuu et al.				
	6,107,143	8/22/2000	Park et al.				
	6,090,684	7/18/2000	Ishitsuka et al.				
	6,066,545	5/23/2000	Doshi et al.				
	6,008,126	12/28/99	Leedy				
	5,946,559	8/31/99	Leedy				
	5,840,593	11/24/98	Leedy				
	5,592,018	1/7/97	Leedy				
	5,592,007	1/7/97	Leedy				
	5,571,741	11/5/96	Leedy				
	5,557,122	9/17/96	Shrivastava et al.				
	5,354,695	10/11/94	Leedy				
	5,134,085	7/28/92	Gilgen et al.				
	5,006,913	4/9/91	Sugahara et al.				
	4,952,524	8/28/90	Lee et al.				
PD	4,855,245	8/8/89	Neppl et al.				

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional): **FIS920030187US1**

Applicant(s): **Chidambarrao, Dureseti, et al.**

Filing Date: **9/22/03**

Application Number: **10/605,310**

Group Art Unit: **Unassigned- 2819**

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

PD		NMOS Drive Current Reduction Caused by Transistor-Layout and Trench Isolation Induced Stress Gregory Scott, et al. 1999 IEEE, 34.4.1-34.4.4, IEDM 99-827
		Transconductance Enhancement in Deep Submicron Strained-Si n- MOSFETs Kern (Ken) Rim, et al. 1998 IEEE, 26.8.1-26.8.4, IEDM 98-707
PD		Characteristics and Device Design of Sub-100 nm Strained Si N- and PMOSFET's K. Rim, et al. 2002 IEEE, 98-99, 2002 Symposium On VLSI Technology Digest of Technical Papers

EXAMINER: **PHUC T. DANG**

DATE CONSIDERED: **11/12/2004**

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.